

# EUROPEAN PATENT OFFICE

## Patent Abstracts of Japan

PUBLICATION NUMBER : 59021038  
PUBLICATION DATE : 02-02-84

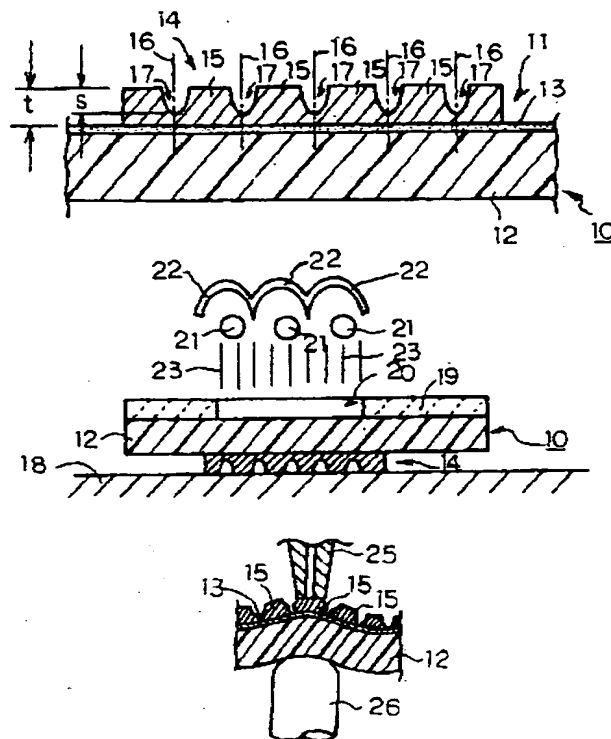
APPLICATION DATE : 27-07-82  
APPLICATION NUMBER : 57130960

APPLICANT : NEC HOME ELECTRONICS LTD;

INVENTOR : YANAGI AKIHIRO;

INT.CL. : H01L 21/68 H01L 21/78

TITLE : RELEASING METHOD FOR PELLET



ABSTRACT : PURPOSE: To prevent the positional displacement and damage of the pellet by a method wherein an ultraviolet curing resin is used as adhesives, a wafer is pasted to an adhesive sheet, ultraviolet rays are made to irradiate a pasted structure to lower adhesive power after dicing work and the pellet is released by a physical means.

CONSTITUTION: The wafer 14 in which a large number of elements such as transistors are manufactured at every partition section is pasted on the adhesive sheet 11 of which ultraviolet curing acryl group adhesives 13 are applied and formed to the surface of a transparent sheet 12 made of polyvinyl chloride. Through-cut grooves 17, 17... cut along the partition section lines 16, 16... of the pellets 15, 15... are set in depth size  $s$  slightly smaller than the thickness size  $t$  of the wafer 14. The surface is coated with an ultraviolet shielding mask 19, and ultraviolet rays 23, 23... generated from high-pressure mercury lamps 21, 21... are bundled into parallel line groups by parabolic concave mirrors 22 and irradiated to an exposed window 20. The adhesives 12 cure and adhesive power lowers remarkably, a vacuum suction collet 25 is brought near previously from an upper section, and the pellets 15 are released through a push-up by releasing bar 26 from a lower section.

COPYRIGHT: (C)1984,JPO&Japio

BEST AVAILABLE COPY